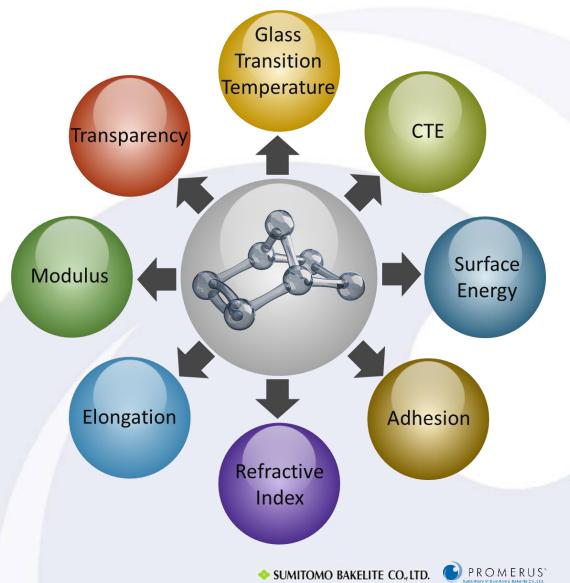
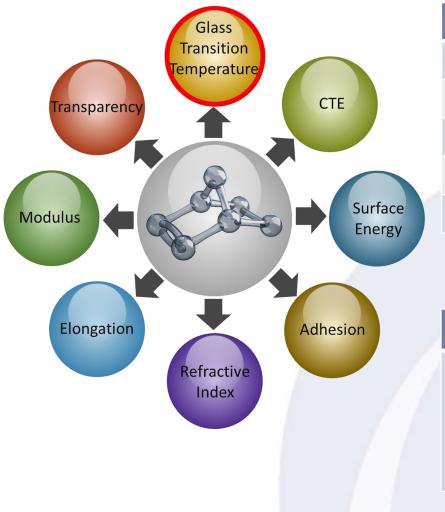
## PNB Polymer Properties are Controlled by Changing the Functional Group (FG)

- Promerus' core technology provides ability to incorporate Functional Groups into PNB backbone
- Other Poly Cyclic Olefins do not offer the same degree of Functional Group tailorability



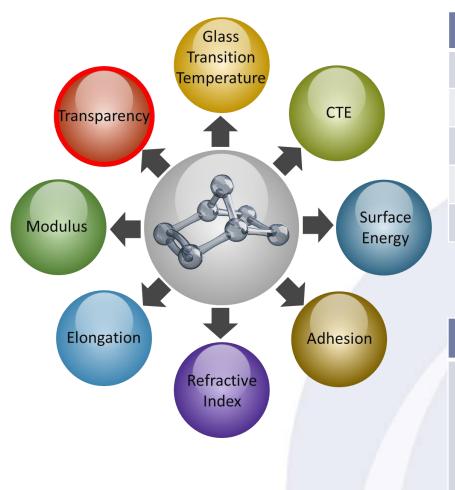
## Glass Transition Temperature Can Be >300°C



Polymer	Τ <sub>g</sub>
Polynorbornene	100-330°C
Polystyrene	90-110°C
PMMA	85-105°C
Zeonex®	69-163°C
Topas®	70-180°C

- Rigid polycyclic backbone yields high Tg
- Other polycyclic olefins lose chain rigidity when flexible co-monomers or ring-opening is employed

## Transparency is high across broad spectrum



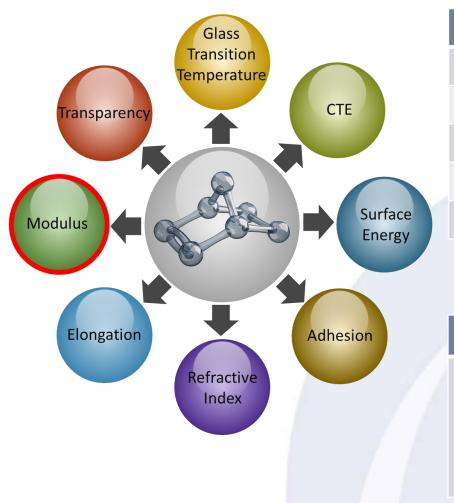
Polymer	Visible transparency
Polynorbornene	>92%
Polystyrene	90%
PMMA	>92%
Zeonex <sup>®</sup>	>92%
Topas®	>92%

#### **Additional Information**

 PNB can be transparent at 157, 193, 365, 405, 436, 1080 and 1550 nm



### Modulus can be high (FG = H) or low (FG = Alkyl)

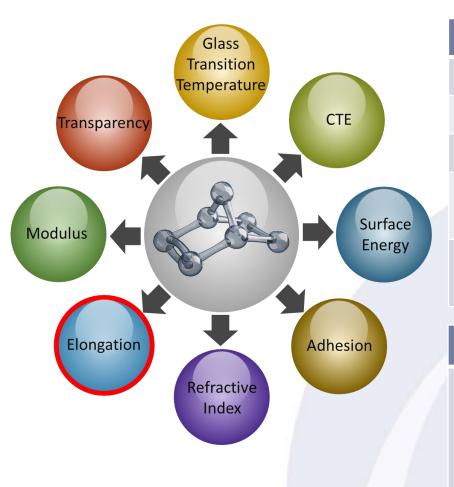


Polymer	Typical
Polynorbornene	0.5 to 3.5 GPa
Polystyrene	3 to 3.5 GPa
PMMA	2.2 to 3.8 GPa
Zeonex <sup>®</sup>	1.8 to 2.4 GPa
Topas <sup>®</sup>	2.6 to 3.2 GPa

- Lower modulus give lower wafer stress
- Lower modulus gives stress compliant layers



## Elongation at break can be low (FG = H) or high (FG = Alkyl)



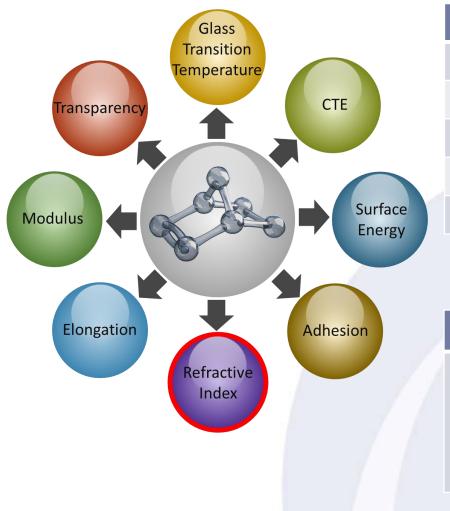
Polymer	Typical
Polynorbornene	5 to 100%
Polystyrene	7%
PMMA	~3%
Zeonex®	10-120% (inversely proportional with Tg)
Topas®	<10% (biaxially oriented films are higher)

#### **Additional Information**

• Crosslinked PNB can retain high elongation at break



## **Refractive index range is broad for PNB**

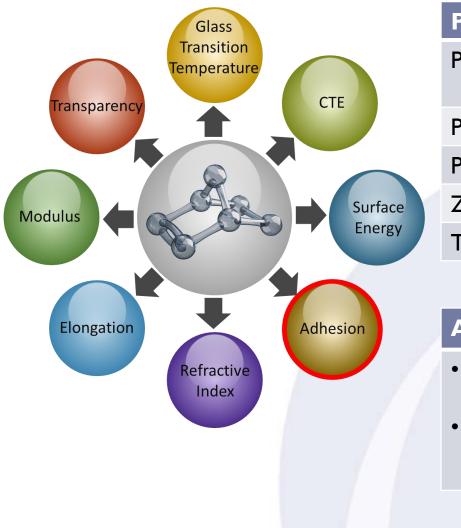


Polymer	Typical (589 nm)
Polynorbornene	1.49 to 1.64+
Polystyrene	1.59
PMMA	1.49
Zeonex <sup>®</sup>	1.51 to 1.53
Topas®	1.53

- Refractive index can be high for all C,H polymer (no hetero-atoms)
- Refractive index can be raised by addition of fillers



## Adhesion is obtained by formulation

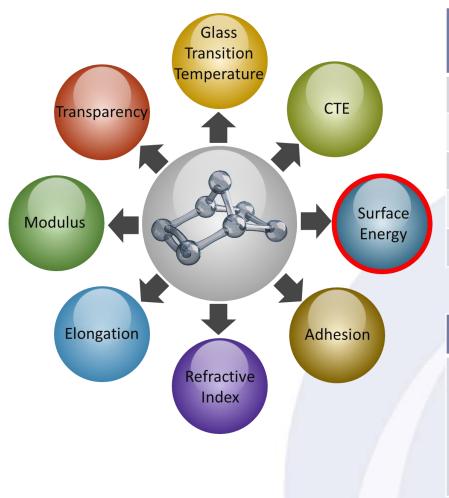


Polymer	Typical
Polynorbornene	$SiO_2$ , $Si_3N_4$ , Cu, Au, Ti, Al, etc
Polystyrene	
PMMA	Unlikely to adhere to
Zeonex <sup>®</sup>	substrates above
Topas <sup>®</sup>	

- Die shear >5 MPa after thermal compression
- Solvent-less polymerization system
  >10 MPa to silicon



## Surface energy can be tailored



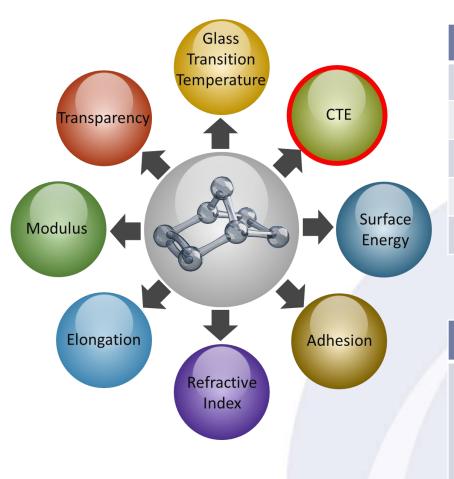
Polymer	Typical (H <sub>2</sub> O contact angle)
Polynorbornene	40° to 109°
Polystyrene	87°
PMMA	71°
Zeonex <sup>®</sup>	>100°
Topas®	>100°

#### **Additional Information**

 Surface energy can be tailored to produce hydrophobic films that are soluble in aqueous base.



## Coefficient of Thermal Expansion (CTE) can be low (FG = H) or high (FG = Alkyl)



Polymer	Typical
Polynorbornene	~50 to >200 ppm/°C
Polystyrene	70 ppm/°C
PMMA	70-77 ppm/°С
Zeonex <sup>®</sup>	60-70 ppm/°С
Topas <sup>®</sup>	60-70 ppm/°С
lopas <sup>™</sup>	60-70 ppm/°C

#### **Additional Information**

CTE depends on crosslink density



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